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AUG 19 2005 ||>g L||>g

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENTS

In Re Application of:

DIANA, Daniel et al.

Serial No.: 10/747,824

Filed: December 29, 2003

Title: METHOD AND APPARATUS FOR  
FILLING INTERLAYER VIAS ON  
FERROELECTRIC POLYMER  
SUBSTRATES

Group Art Unit: 2823

T. D

Examiner: DANG, Trung Q.

8/26/05

Atty. Docket #: INTEL16

Assignee: Intel Corporation

O.K TO ENTER

AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This submission is in response to the Final Official Action mailed by the U.S. Patent and Trademark Office on June 16, 2005. As of this Official Action, pending claims 1 - 9, and 22 - 25 are allowed, claims 13 - 15 stand rejected, and claims 16, 17, and 19 - 21 are objected to. In response to this Final Official Action, it is respectfully requested that the Office consider the following remarks and amendments to the above-referenced application.